

Title (en)

A SPRING CLIP FOR MOUNTING A HEAT SINK TO AN ELECTRONIC COMPONENT

Title (de)

FEDERKLAMMER ZUR MONTAGE EINES KÜHLKÖRPERS AUF EINEM ELEKTRONISCHEN ELEMENT

Title (fr)

BRIDE ELASTIQUE POUR MONTAGE DE Puits DE CHALEUR SUR COMPOSANT ELECTRONIQUE

Publication

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Application

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Abstract (en)

[origin: WO9835540A1] A heat sink spring clip (14) having a linearly displaceable deflection member (11) that operatively engages a biasing member (10) for thermally and mechanically connecting a heat sink (3) to an electronic component (2). The deflection member (11) is moveable in a generally linear manner on and relative to the biasing member (10) between a first position of non engagement in which the biasing member (10) is substantially undeflected and a second position in which the biasing member (10) is deflected and the deflection member (11) is contactingly and operatively engaged with the heat sink (3) for thermally and mechanically connecting the heat sink (3) to an electronic component (2). As the deflection member (11) is moved from the disengaged position to the engaged position, complementary elements on the biasing member (10) and deflection member (11) engage one another and cause portions of the deflection and biasing members (10, 11) to move relatively apart. As the biasing member (10) deflects in one direction generally away from the heat sink (3), the biasing member (10) simultaneously imparts a generally oppositely directed compression force onto the heat sink (3) and electrical components (2) adjacently stacked therebeneath through the deflection member (11). The deflection member (11) is operatively moveable in a generally horizontal direction longitudinally on and along the biasing member (10) or, in an alternate embodiment, in a direction substantially transverse to the elongation of the biasing member (10).

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